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SN65LBC176A-EP
DIFFERENTIAL BUS TRANSCEIVER

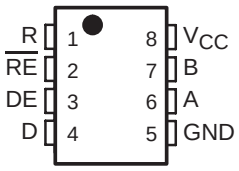
SGLS151C – DECEMBER 2002 – REVISED JULY 2004

- **Controlled Baseline**
  - **One Assembly/Test Site, One Fabrication Site**
- **Extended Temperature Performance of −40°C to 125°C and −55°C to 125°C**
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product Change Notification**
- **Qualification Pedigree†**
- **High-Speed Low-Power LinBiCMOS™ Circuitry Designed for Signaling Rates‡ Up to 30 Mbps**
- **Bus-Pin ESD Protection Exceeds 12-kV HBM**
- **Compatible With ANSI Standard TIA/EIA-485-A and ISO 8482:1987(E)**
- **Low Skew**
- **Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments**
- **Low Disabled Supply Current Requirements . . . 700 μA Maximum**
- **Common-Mode Voltage Range of −7 V to 12 V**
- **Thermal-Shutdown Protection**
- **Driver Positive and Negative Current Limiting**
- **Open-Circuit Fail-Safe Receiver Design**
- **Receiver Input Sensitivity . . . ±200 mV Max**
- **Receiver Input Hysteresis . . . 50 mV Typ**
- **Glitch-Free Power-Up and Power-Down Protection**

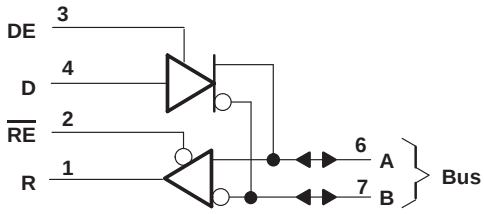
† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

‡ Signaling rate by TIA/EIA-485-A definition restrict transition times to 30% of the bit length, and much higher signaling rates may be achieved without this requirement as displayed in the *TYPICAL CHARACTERISTICS* of this device.

D Package
(TOP VIEW)



logic diagram (positive logic)



Function Tables

DRIVER

INPUT D	ENABLE DE	OUTPUTS A	OUTPUTS B
H	H	H	L
L	H	L	H
X	L	Z	Z
Open	H	H	L

RECEIVER

DIFFERENTIAL INPUTS $V_A - V_B$	ENABLE $\overline{RE}$	OUTPUT R
$V_{ID} \geq 0.2$ V	L	H
-0.2 V $< V_{ID} < 0.2$ V	L	?
$V_{ID} \leq -0.2$ V	L	L
X	H	Z
Open	L	H

H = high level, L = low level, ? = indeterminate,
X = irrelevant, Z = high impedance (off)

description/ordering information

The SN65LBC176A-EP differential bus transceiver is a monolithic, integrated circuits designed for bidirectional data communication on multipoint bus-transmission lines. The SN65LBC176A-EP is designed for balanced transmission lines and is compatible with ANSI standard TIA/EIA-485-A and ISO 8482. The SN65LBC176A-EP offers improved switching performance over its predecessors without sacrificing significantly more power.

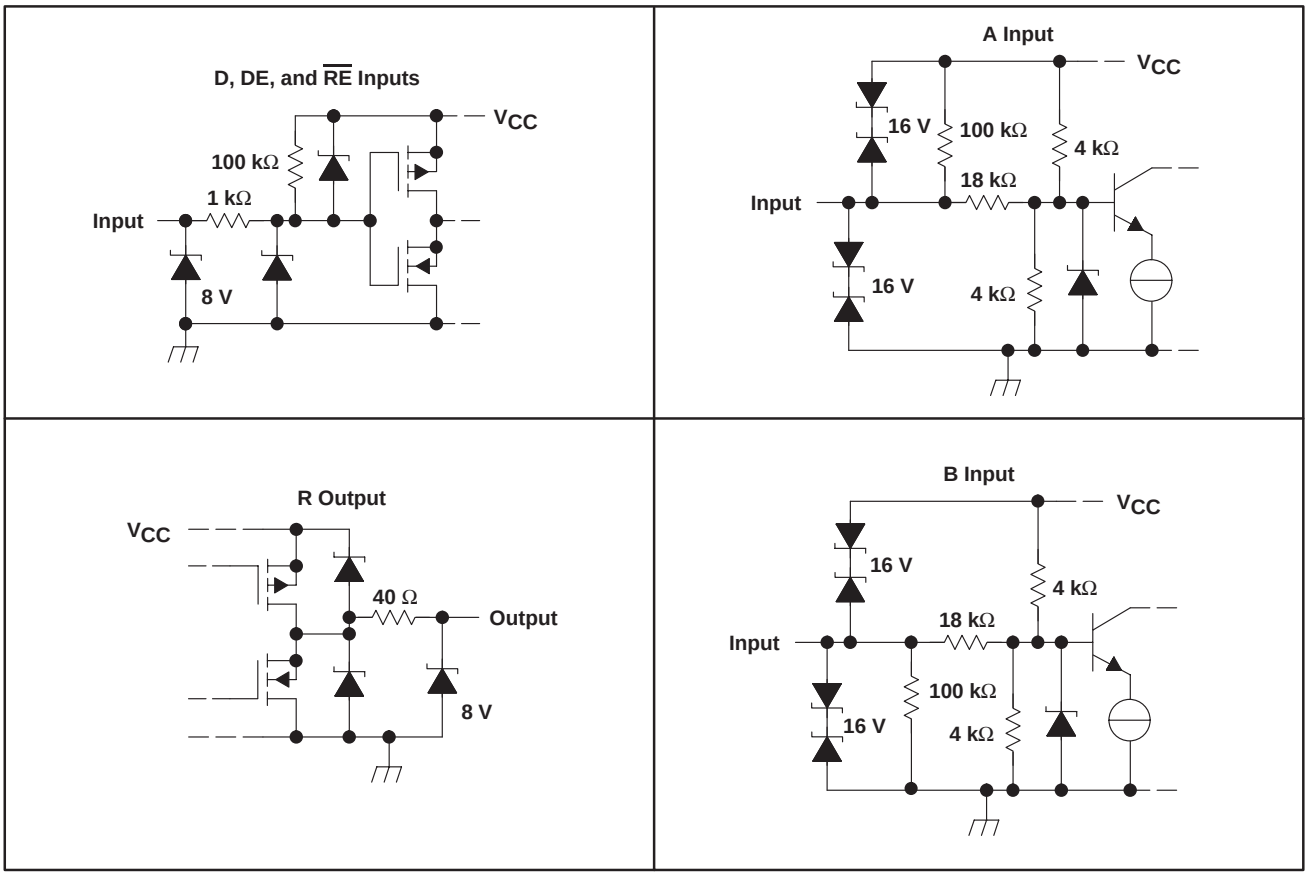
The SN65LBC176A-EP combines a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can externally connect together to function as a direction control. The driver differential outputs and the receiver differential inputs connect internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus whenever the driver is disabled or V_{CC} = 0. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications. Low device supply current can be achieved by disabling the driver and the receiver.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 125°C	SOIC − D	Tape and Reel	SN65LBC176AQDREP	176AEP
−55°C to 125°C	SOIC − D	Tape and Reel	SN65LBC176AMDREP	176MEP

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

schematics of inputs and outputs



absolute maximum ratings†

Supply voltage, V_{CC} (see Note 1) . . . . . −0.3 V to 6 V
Voltage range at any bus terminal (A or B) . . . . . −10 V to 15 V
Input voltage, V_I (D, DE, R, or $\overline{RE}$) . . . . . −0.3 V to V_{CC} + 0.5 V
Electrostatic discharge: Bus terminals and GND, Class 3, A: (see Note 2) . . . . . 12 kV
Bus terminals and GND, Class 3, B: (see Note 2) . . . . . 400 V
All terminals, Class 3, A: . . . . . 4 kV
All terminals, Class 3, B: . . . . . 400 V
Continuous total power dissipation (see Note 3) . . . . . See Dissipation Rating Table
Storage temperature range, T_{stg} (see Note 4) . . . . . −65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds . . . . . 260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

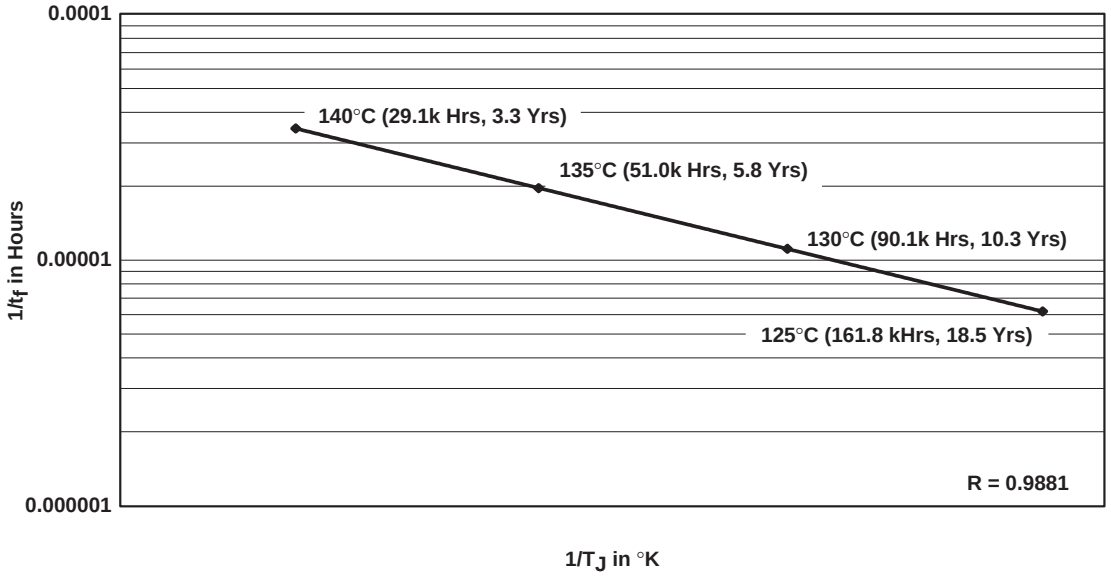
NOTES: 1. All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.
2. The maximum operating junction temperature is internally limited. Use the dissipation rating table to operate below this temperature.
3. Tested in accordance with MIL−STD−883C, Method 3015.7
4. Long-term, high-temperature storage and/or extended use at maximum recommended operating conditions may result in a reduction of overall device life. See http://www.ti.com/ep_quality for additional information on enhanced plastic packaging.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR‡ ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 85°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW

‡ This is the inverse of the junction-to-ambient thermal resistance when the board is mounted and with no air flow.

OPERATING LIFE DERATING TABLE − SN65LBC176AMDREP
$1/t_f$ vs $1/T_J$ in °K



NOTES: A. See the data sheet for absolute maximum and maximum recommended operating conditions.
B. Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).
C. Attached enhanced plastic product disclaimer applies.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.75	5	5.25	V
Voltage at any bus terminal (separately or common mode), V_I or V_{IC}				12	V
		−7			
High-level input voltage, V_{IH} (output recessive)	D, DE, and $\overline{RE}$	2		V_{CC}	V
Low-level input voltage, V_{IL} (output dominant)	D, DE, and $\overline{RE}$	0		0.8	V
Differential input voltage, V_{ID} (see Note 5)		−12§		12	V
High-level output current, I_{OH}	Driver	−60			mA
	Receiver	−8			
Low-level output current, I_{OL}	Driver			60	mA
	Receiver			8	
Operating free-air temperature, T_A	SN65LBC176AQ-EP	−40		125	°C
	SN65LBC176AM-EP	−55		125	

§ The algebraic convention, in which the least positive (most negative) limit is designated as minimum, is used in this data sheet.
NOTE 5: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.

driver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	Input clamp voltage	I_I = −18 mA		−1.5	−0.8		V
$\lvert V_{OD} \rvert$	Differential output voltage	I_O = 0		1.5	4	6	V
		R_L = 54 Ω, See Figure 1		0.9	1.5	6	
		V_{test} = −7 V to 12 V, See Figure 2		0.9	1.5	6	
$\Delta\lvert V_{OD} \rvert$	Change in magnitude of differential output voltage	See Figure 1 and Figure 2		−0.2		0.2	V
$V_{OC(SS)}$	Steady-state common-mode output voltage	See Figure 1		1.8	2.4	3	V
$\Delta V_{OC(SS)}$	Change in steady-state common-mode output voltage†	See Figure 1		−0.2		0.2	V
I_{OZ}	High-impedance output current	See receiver input currents					
I_{IH}	High-level enable input current	V_I = 2 V		−100			µA
I_{IL}	Low-level enable input current	V_I = 0.8 V		−100			µA
I_{OS}	Short-circuit output current	−7 V ≤ V_O ≤ 12 V		−250	±70	250	mA
I_{CC}	Supply current	V_I = 0 or V_{CC}, No load	Receiver disabled and driver enabled		5	9	mA
			Receiver disabled and driver disabled		0.4	0.7	
			Receiver enabled and driver enabled		8.5	15	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

driver switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, low-to-high level output	R_L = 54 Ω, C_L = 50 pF, See Figure 3	2		12	ns
t_{PHL}	Propagation delay time, high-to-low level output		2		12	
$t_{sk(p)}$	Pulse skew ($\lvert t_{PLH} - t_{PHL} \rvert$)				2	
t_r	Differential output signal rise time		1.2		11	
t_f	Differential output signal fall time		1.2		11	
t_{PZH}	Propagation delay time, high-impedance to high-level output	R_L = 110 Ω, See Figure 4			22	ns
t_{PZL}	Propagation delay time, high-impedance to low-level output	R_L = 110 Ω, See Figure 5			25	ns
t_{PHZ}	Propagation delay time, high-level to high-impedance output	R_L = 110 Ω, See Figure 4			22	ns
t_{PLZ}	Propagation delay time, low-level to high-impedance output	R_L = 110 Ω, See Figure 5			22	ns

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

receiver electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	I_O = −8 mA				0.2	V
V_{IT-}	Negative-going input threshold voltage	I_O = 8 mA		−0.2			V
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)				50		mV
V_{IK}	Enable-input clamp voltage	I_I = −18 mA		−1.5	−0.8		V
V_{OH}	High-level output voltage	V_{ID} = 200 mV, I_{OH} = −8 mA, See Figure 6		4	4.9		V
V_{OL}	Low-level output voltage	V_{ID} = 200 mV, I_{OL} = 8 mA, See Figure 6			0.1	0.8	V
I_{OZ}	High-impedance-state output current	V_O = 0 to V_{CC}		−10		10	µA
I_I	Bus input current	V_{IH} = 12 V, V_{CC} = 5 V	Other input at 0 V		0.4	1	mA
		V_{IH} = 12 V, V_{CC} = 0			0.5	1	
		V_{IH} = −7 V, V_{CC} = 5 V		−0.8	−0.4		
		V_{IH} = −7 V, V_{CC} = 0		−0.8	−0.3		
I_{IH}	High-level enable-input current	V_{IH} = 2 V		−100			µA
I_{IL}	Low-level enable-input current	V_{IL} = 0.8 V		−100			µA
I_{CC}	Supply current	V_I = 0 or V_{CC}, No load	Receiver enabled and driver disabled		4	7	mA
			Receiver disabled and driver disabled		0.4	0.7	
			Receiver enabled and driver enabled		8.5	15	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

receiver switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PLH}	Propagation delay time, output↑	V_{ID} = −1.5 V to 1.5 V, See Figure 7	7		30	ns
t_{PHL}	Propagation delay time, output↓		7		30	ns
$t_{sk(p)}$	Pulse skew ($\lvert t_{PHL} - t_{PLH} \rvert$)				6	ns
t_r	Rise time, output	See Figure 7			5	ns
t_f	Fall time, output				5	ns
t_{PZH}	Output enable time to high level	C_L = 10 pF, See Figure 8			50	ns
t_{PZL}	Output enable time to low level				50	ns
t_{PHZ}	Output disable time from high level				60	ns
t_{PLZ}	Output disable time from low level				40	ns

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

PARAMETER MEASUREMENT INFORMATION

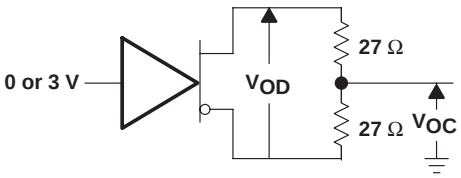


Figure 1. Driver V_{OD} and V_{OC}

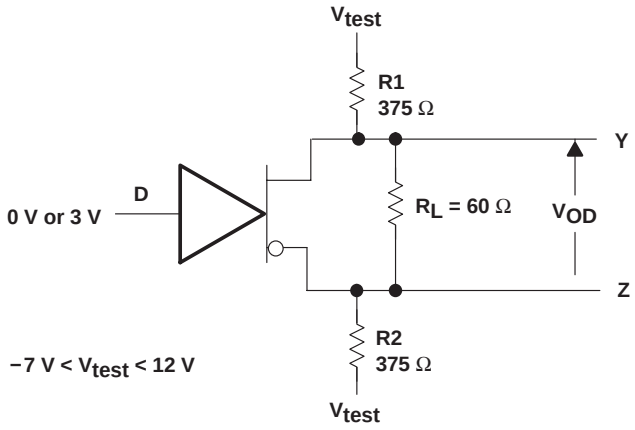
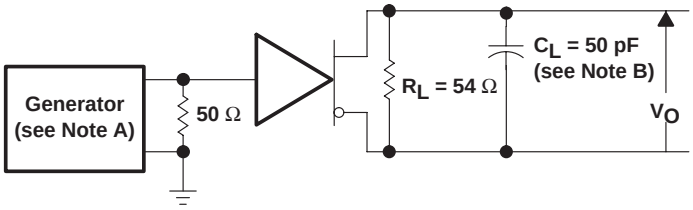
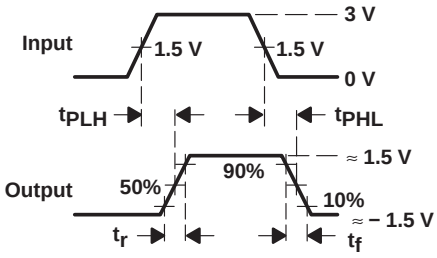


Figure 2. Driver V_{OD3}



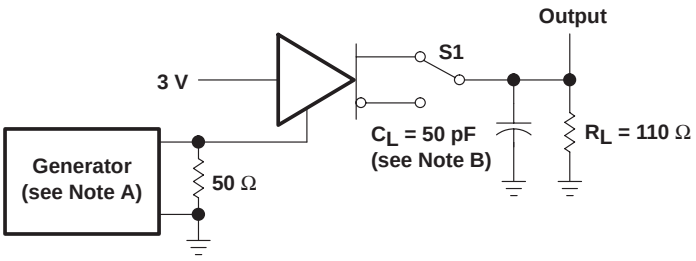
TEST CIRCUIT



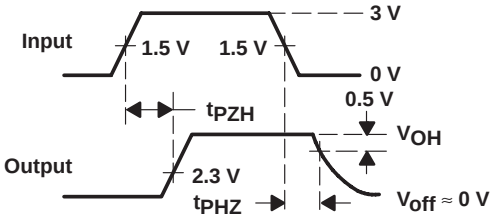
VOLTAGE WAVEFORMS

NOTES: D. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
E. C_L includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms



TEST CIRCUIT

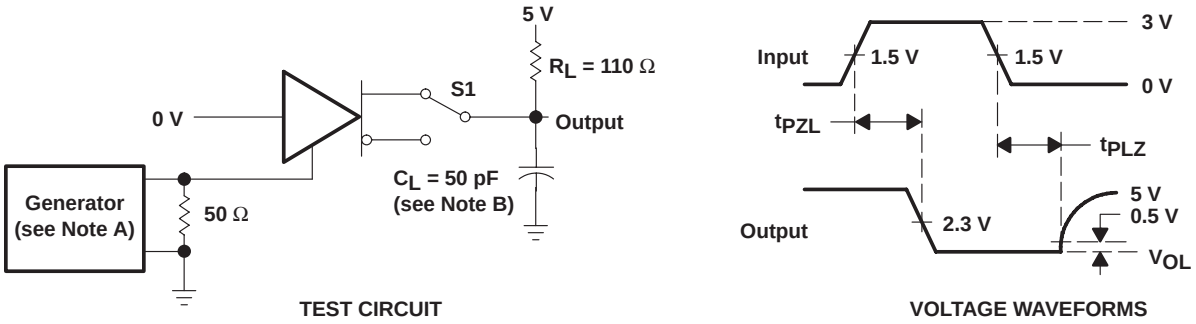


VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 4. Driver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 5. Driver Test Circuit and Voltage Waveforms

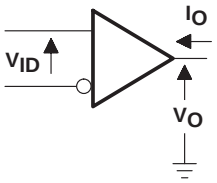
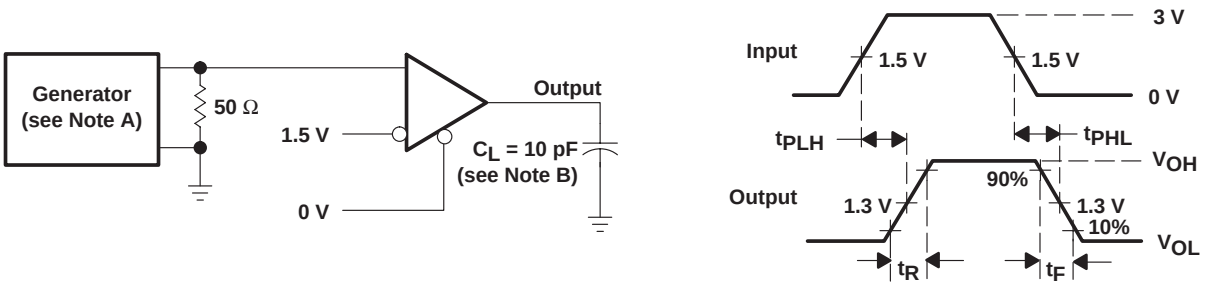


Figure 6. Receiver V_{OH} and V_{OL}

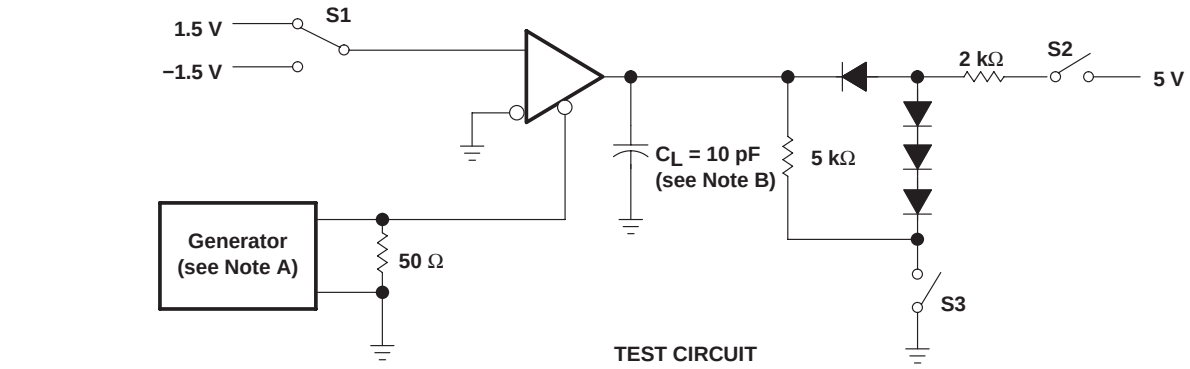


TEST CIRCUIT VOLTAGE WAVEFORMS

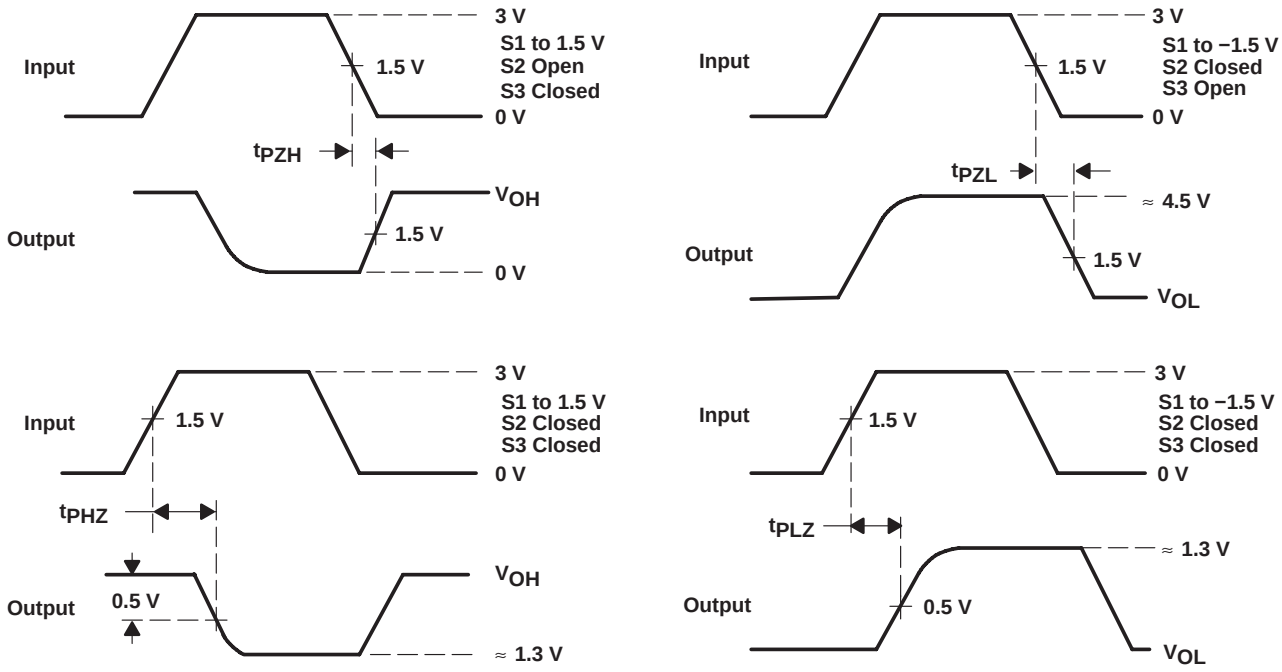
NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR ≤ 1 MHz, 50% duty cycle, t_r ≤ 6 ns, t_f ≤ 6 ns, Z_O = 50 Ω.
B. C_L includes probe and jig capacitance.

Figure 8. Receiver Test Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS

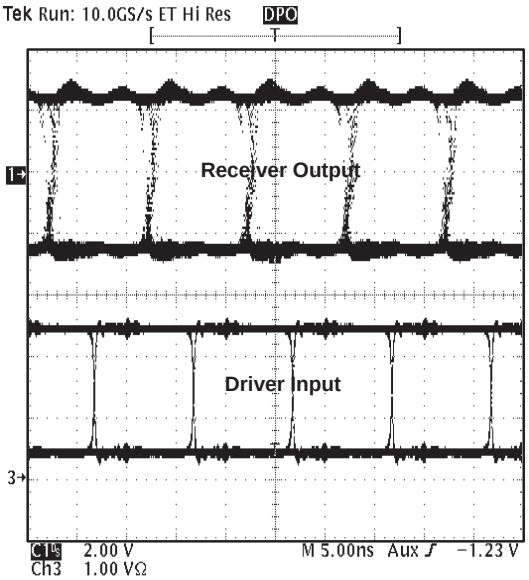


Figure 9. Typical Waveform of Non-Return-To-Zero (NRZ), Pseudorandom Binary Sequence (PRBS) Data at 100 Mbps Through 15m, of CAT 5 Unshielded Twisted Pair (UTP) Cable

TIA/EIA-485-A defines a maximum signaling rate as that in which the transition time of the voltage transition of a logic-state change remains less than or equal to 30% of the bit length. Transition times of greater length perform quite well, even though they do not meet the standard by definition.

TYPICAL CHARACTERISTICS

AVERAGE SUPPLY CURRENT
vs
FREQUENCY

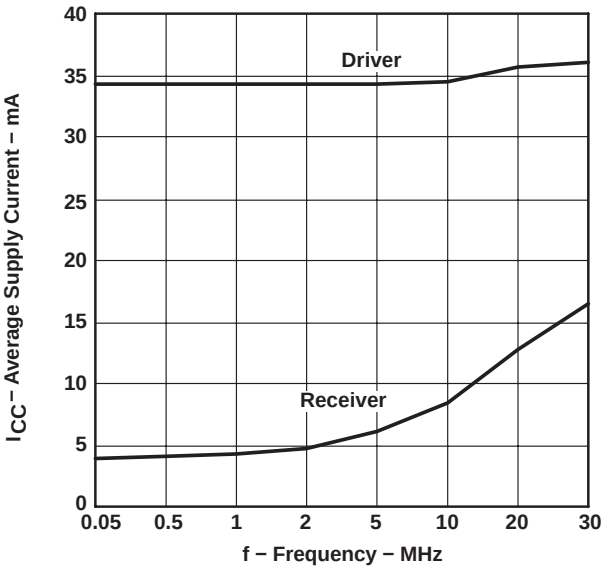


Figure 10

LOGIC INPUT CURRENT
vs
INPUT VOLTAGE

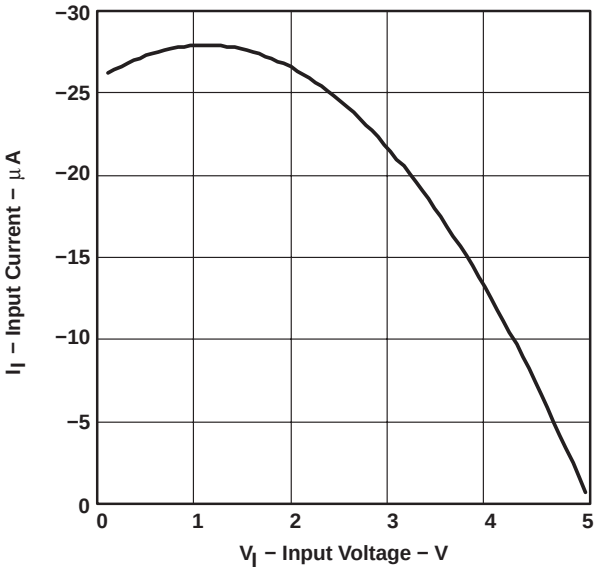


Figure 11

INPUT CURRENT
vs
INPUT VOLTAGE

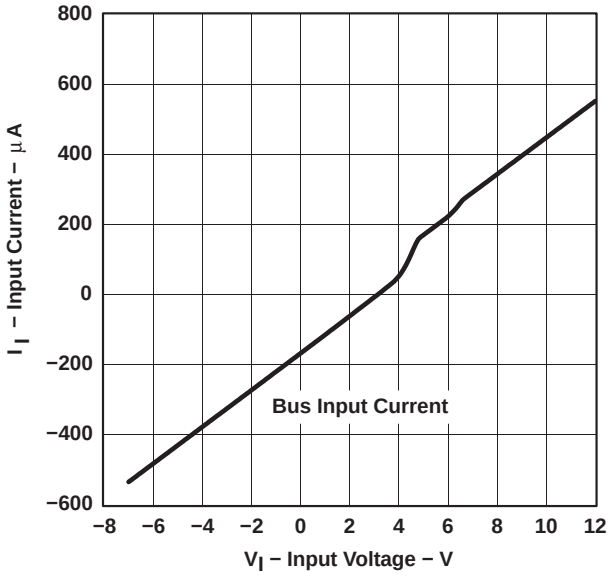


Figure 12

LOW-LEVEL OUTPUT VOLTAGE
vs
LOW-LEVEL OUTPUT CURRENT

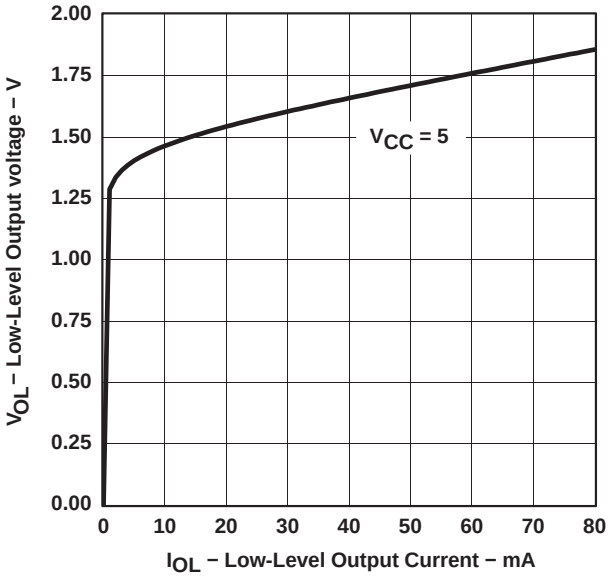


Figure 13

TYPICAL CHARACTERISTICS

DRIVER HIGH-LEVEL OUTPUT VOLTAGE
vs
HIGH-LEVEL OUTPUT CURRENT

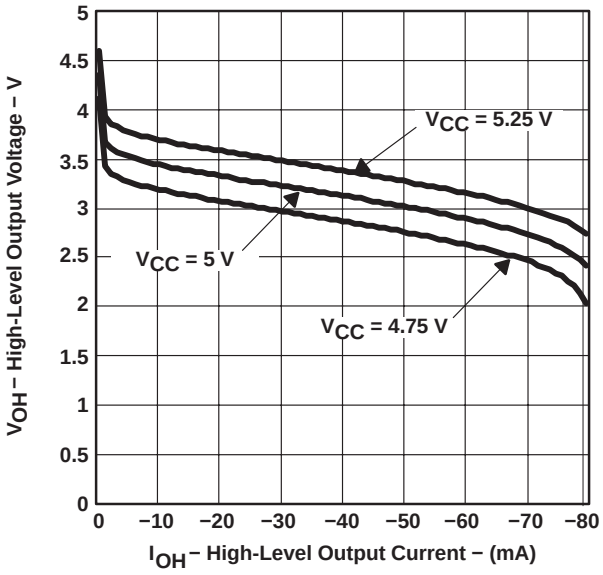


Figure 14

DRIVER DIFFERENTIAL OUTPUT VOLTAGE
vs
AVERAGE CASE TEMPERATURE

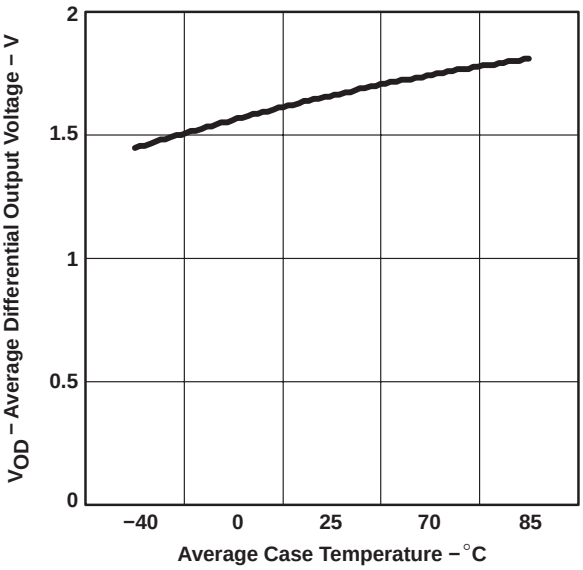


Figure 15

RECEIVER PROPAGATION TIME
vs
CASE TEMPERATURE

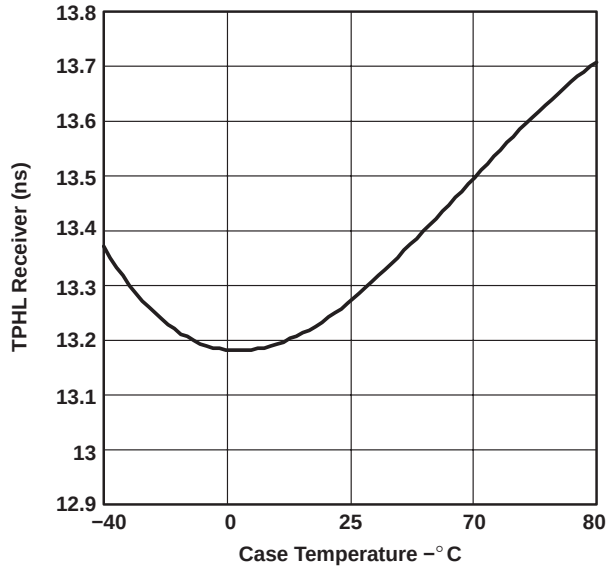


Figure 16

DRIVER PROPAGATION DELAY TIME
vs
CASE TEMPERATURE

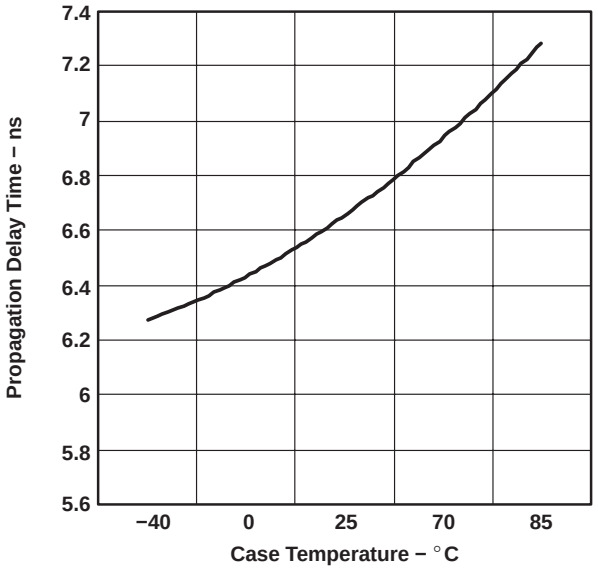


Figure 17

TYPICAL CHARACTERISTICS

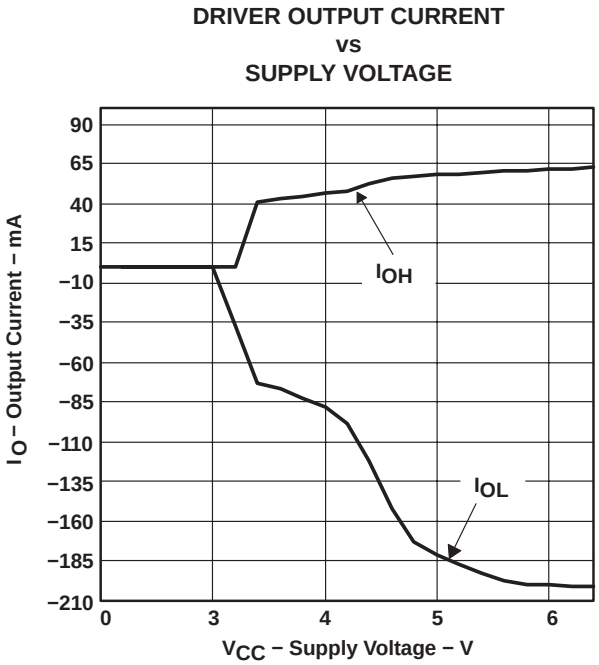


Figure 18

TEXAS INSTRUMENTS
www.ti.com

PACKAGE OPTION ADDENDUM

18-Sep-2008

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN65LBC176AMDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN65LBC176AQDREP	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03671-01XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03671-02XE	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

OTHER QUALIFIED VERSIONS OF SN65LBC176A-EP :
- Catalog: SN65LBC176A

NOTE: Qualified Version Definitions:
- Catalog - TI's standard catalog product

TEXAS INSTRUMENTS
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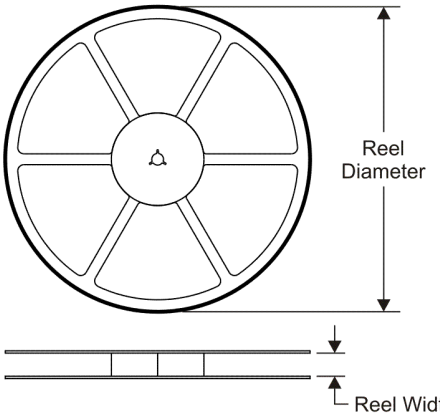
PACKAGE MATERIALS INFORMATION

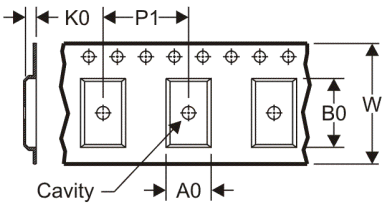
5-Jul-2008

TAPE AND REEL INFORMATION

REEL DIMENSIONS

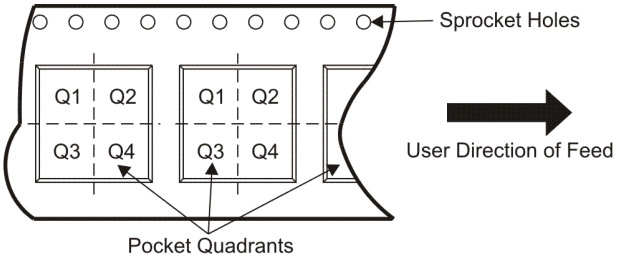


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



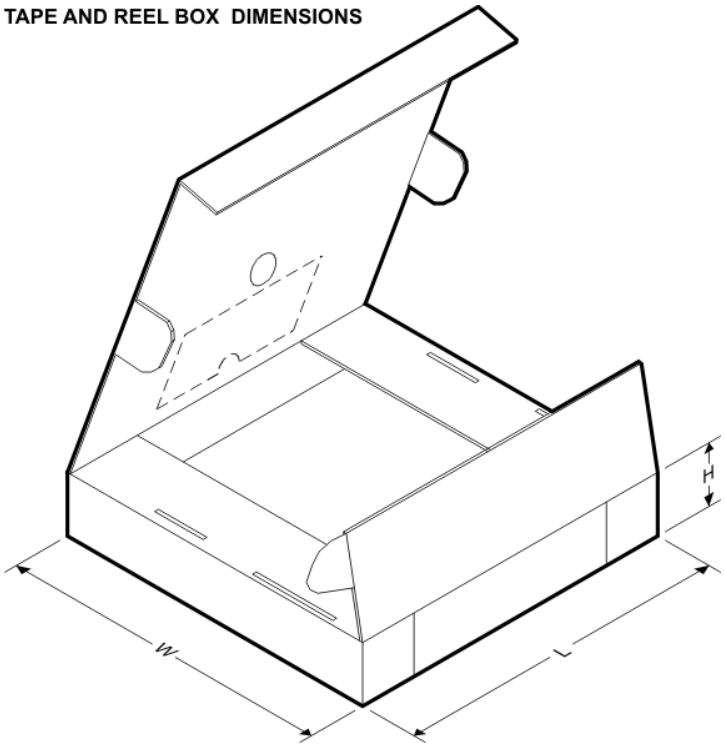
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65LBC176AMDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
SN65LBC176AQDREP	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

5-Jul-2008

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65LBC176AMDREP	SOIC	D	8	2500	346.0	346.0	29.0
SN65LBC176AQDREP	SOIC	D	8	2500	346.0	346.0	29.0

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